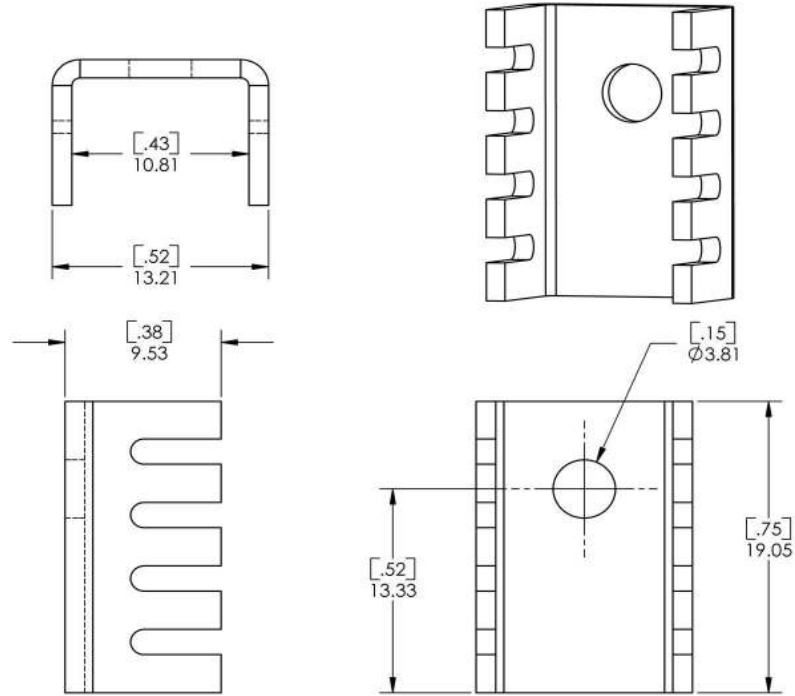
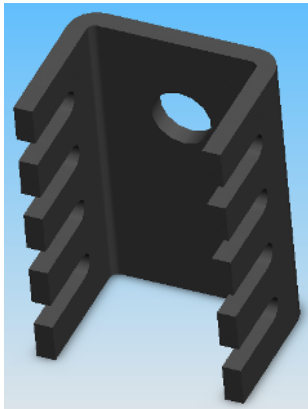


# Board Level Heat Sinks



ThermaFlo

**P/N: 821102B00000**



## PRODUCT SPECIFICATIONS

- Devices: TO-220
- Size: 9.5 x 13.2 x 19.1 mm
- Material: Aluminum, 1.2 mm Thick
- Weight: 1.5 grams
- Type: Stamped
- PCB Mounting: Device Leads
- Finish: Black Anodized
- Package: Bulk
- Accessories: Hardware & Thermal Interface Material

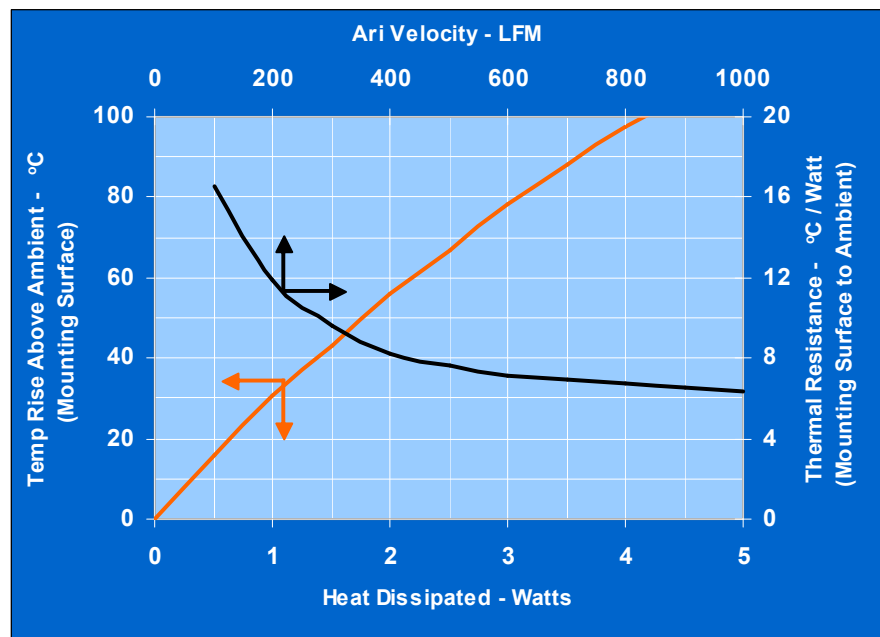
## FEATURES & BENEFITS

- Hole for Device Attachment
- RoHS Compliant



## CUSTOMIZED HEATSINKS

- Specialized Tabs, Plating
- Specialized Body Configurations
- Contact Applications Engineering



**TO-220**

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